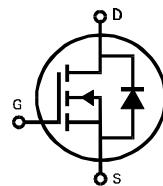


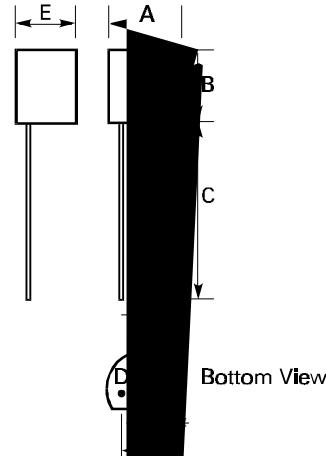
## N-CHANNEL ENHANCEMENT MODE FIELD EFFECT TRANSISTOR

### Features

- Efficient high density cell design approaching 3 million per square inch
- Voltage controlled small signal switch
- Rugged
- High saturation current
- Low  $R_{DS(ON)}$
- Fast Switching Speed



**TO-92**



### Mechanical Data

- TO-92 Plastic Case
- Leads: Solderable per MIL-STD-202, Method 208
- Pin Connections: See Diagram
- Marking: Type Number
- Weight: 0.18 gram (approx.)

	Min	Max
A	4.45	4.70
B	4.46	4.70
C	12.7	—
D	0.41	0.63
E	3.43	3.68
G	2.42	2.67
All dimensions	mm	mm

### Maximum Ratings

@ TA = 25°C unless otherwise noted

Symbol	Parameter	2N7000	Units
$V_{DSS}$	Drain-Source Voltage	60	V
$V_{DGR}$	Drain-Gate Voltage RGS $\leq 1\text{M}\Omega$	60	V
$V_{GSS}$	Gate-Source Voltage	$\pm 40$	V
$I_D$	Drain Current—Continuous —Pulsed*	200 500	mA mA
$P_D$	Total Power Dissipation Derating above 25°C	400 3.2	mW mW/°C
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	°C
$T_L$	Maximum Lead Temperature for Soldering Purposes, 1.5mm from Case for 10 seconds	300	°C

\*Pulse Width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$

## Electrical Characteristics

$T_A = 25^\circ\text{C}$  Unless otherwise specified

Symbol	Parameter	Conditions	Min	Max	Units
<b>Off Characteristics</b>					
$B_{VDSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}, I_D = 10\mu\text{A}$	60		V
$I_{DS(0)}$	Zero Gate Voltage Drain Current	$V_{DS} = 48\text{V}, V_{GS} = 0\text{V}$ $(T_J = 125^\circ\text{C})$		1 1	$\mu\text{A}$ $\text{mA}$
$I_{GSS}$	Gate-Body Leakage	$V_{GS} = \pm 15\text{V}, V_{DS} = 0\text{V}$		$\pm 10$	nA
<b>On Characteristics*</b>					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 1\text{mA}$	0.8	3	V
$r_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{V}, I_D = 0.5\text{A}$ $(T_J = 125^\circ\text{C})$		5 9	$\Omega$ $\Omega$
$V_{DS(on)}$	Drain-Source On-Voltage	$V_{GS} = 10\text{V}, I_D = 0.5\text{A}$ $V_{GS} = 4.5\text{V}, I_D = 75\text{mA}$		2.5 0.4	V V
$I_{D(on)}$	On-State Drain Current	$V_{GS} = 4.5\text{V}, V_{DS} = 10\text{V}$	75		mA
$g_{FS}$	Forward Transconductance	$V_{DS} = 10\text{V}, I_D = 200\text{mA}$	100		millimhos
<b>Dynamic Characteristics</b>					
$C_{iss}$	Input Capacitance	$V_{DS} = 25, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$		50	pF
$C_{oss}$	Output Capacitance			25	pF
$C_{rss}$	Reverse Transfer Capacitance			5	pF
<b>Switching Characteristics*</b>					
$t_{on}$	Turn-On Time	$V_{DD} = 15\text{V}, I_D = 0.5\text{A}, V_{GS} = 10\text{V},$ $R_{GEN} = 25\Omega, R_L = 25\Omega$		10	ns
$t_{off}$	Turn-Off Time			10	ns
<b>Body-Drain Diode Ratings</b>					
$I_S$	Maximum Continuous Drain-Source Diode Forward Current		200		mA
$I_{SM^*}$	Maximum Pulsed Drain-Source Diode Forward Current		500		mA
$V_{SD^*}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = 200\text{mA}$		1.5	V
<b>Thermal Characteristics</b>					
$R_{Theta A}$	Thermal Resistance, Junction to Ambient		312.5		°C/W

\* Pulse Test: Pulse Width  $\leq 300\ \mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .